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Understanding [Embedded - CPLDs \(Complex Programmable Logic Devices\)](#)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details

Product Status	Active
Programmable Type	In System Programmable
Delay Time tpd(1) Max	7.5 ns
Voltage Supply - Internal	3V ~ 3.6V
Number of Logic Elements/Blocks	16
Number of Macrocells	256
Number of Gates	-
Number of I/O	128
Operating Temperature	-40°C ~ 105°C (TJ)
Mounting Type	Surface Mount
Package / Case	176-LQFP
Supplier Device Package	176-TQFP (24x24)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lc4256v-75tn176i

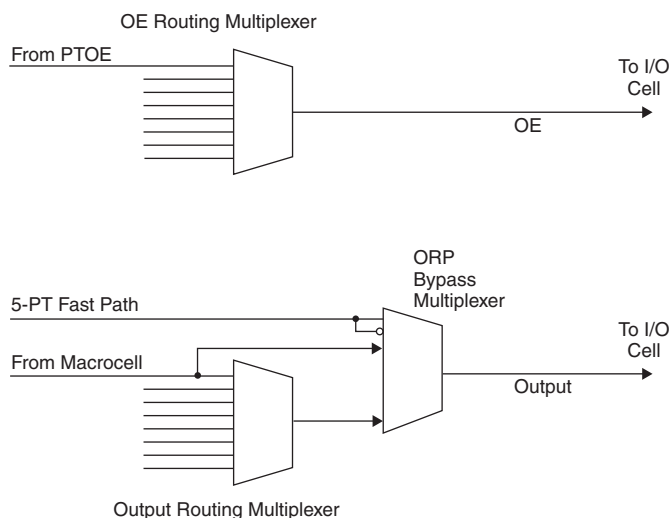
Output Routing Pool (ORP)

The Output Routing Pool allows macrocell outputs to be connected to any of several I/O cells within an I/O block. This provides greater flexibility in determining the pinout and allows design changes to occur without affecting the pinout. The output routing pool also provides a parallel capability for routing macrocell-level OE product terms. This allows the OE product term to follow the macrocell output as it is switched between I/O cells. Additionally, the output routing pool allows the macrocell output or true and complement forms of the 5-PT bypass signal to bypass the output routing multiplexers and feed the I/O cell directly. The enhanced ORP of the ispMACH 4000 family consists of the following elements:

- Output Routing Multiplexers
- OE Routing Multiplexers
- Output Routing Pool Bypass Multiplexers

Figure 7 shows the structure of the ORP from the I/O cell perspective. This is referred to as an ORP slice. Each ORP has as many ORP slices as there are I/O cells in the corresponding I/O block.

Figure 7. ORP Slice



Output Routing Multiplexers

The details of connections between the macrocells and the I/O cells vary across devices and within a device dependent on the maximum number of I/Os available. Tables 5-9 provide the connection details.

Table 6. ORP Combinations for I/O Blocks with 8 I/Os

I/O Cell	Available Macrocells
I/O 0	M0, M1, M2, M3, M4, M5, M6, M7
I/O 1	M2, M3, M4, M5, M6, M7, M8, M9
I/O 2	M4, M5, M6, M7, M8, M9, M10, M11
I/O 3	M6, M7, M8, M9, M10, M11, M12, M13
I/O 4	M8, M9, M10, M11, M12, M13, M14, M15
I/O 5	M10, M11, M12, M13, M14, M15, M0, M1
I/O 6	M12, M13, M14, M15, M0, M1, M2, M3
I/O 7	M14, M15, M0, M1, M2, M3, M4, M5

Supply Current, ispMACH 4000V/B/C

Over Recommended Operating Conditions

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
ispMACH 4032V/B/C						
ICC ^{1,2,3}	Operating Power Supply Current	V _{CC} = 3.3V	—	11.8	—	mA
		V _{CC} = 2.5V	—	11.8	—	mA
		V _{CC} = 1.8V	—	1.8	—	mA
ICC ⁴	Standby Power Supply Current	V _{CC} = 3.3V	—	11.3	—	mA
		V _{CC} = 2.5V	—	11.3	—	mA
		V _{CC} = 1.8V	—	1.3	—	mA
ispMACH 4064V/B/C						
ICC ^{1,2,3}	Operating Power Supply Current	V _{CC} = 3.3V	—	12	—	mA
		V _{CC} = 2.5V	—	12	—	mA
		V _{CC} = 1.8V	—	2	—	mA
ICC ⁵	Standby Power Supply Current	V _{CC} = 3.3V	—	11.5	—	mA
		V _{CC} = 2.5V	—	11.5	—	mA
		V _{CC} = 1.8V	—	1.5	—	mA
ispMACH 4128V/B/C						
ICC ^{1,2,3}	Operating Power Supply Current	V _{CC} = 3.3V	—	12	—	mA
		V _{CC} = 2.5V	—	12	—	mA
		V _{CC} = 1.8V	—	2	—	mA
ICC ⁴	Standby Power Supply Current	V _{CC} = 3.3V	—	11.5	—	mA
		V _{CC} = 2.5V	—	11.5	—	mA
		V _{CC} = 1.8V	—	1.5	—	mA
ispMACH 4256V/B/C						
I _{CC} ^{1,2,3}	Operating Power Supply Current	V _{CC} = 3.3V	—	12.5	—	mA
		V _{CC} = 2.5V	—	12.5	—	mA
		V _{CC} = 1.8V	—	2.5	—	mA
I _{CC} ⁴	Standby Power Supply Current	V _{CC} = 3.3V	—	12	—	mA
		V _{CC} = 2.5V	—	12	—	mA
		V _{CC} = 1.8V	—	2	—	mA
ispMACH 4384V/B/C						
I _{CC} ^{1,2,3}	Operating Power Supply Current	V _{CC} = 3.3V	—	13.5	—	mA
		V _{CC} = 2.5V	—	13.5	—	mA
		V _{CC} = 1.8V	—	3.5	—	mA
I _{CC} ⁴	Standby Power Supply Current	V _{CC} = 3.3V	—	12.5	—	mA
		V _{CC} = 2.5V	—	12.5	—	mA
		V _{CC} = 1.8V	—	2.5	—	mA
ispMACH 4512V/B/C						
I _{CC} ^{1,2,3}	Operating Power Supply Current	V _{CC} = 3.3V	—	14	—	mA
		V _{CC} = 2.5V	—	14	—	mA
		V _{CC} = 1.8V	—	4	—	mA

I/O DC Electrical Characteristics

Over Recommended Operating Conditions

Standard	V_{IL}		V_{IH}		V_{OL} Max (V)	V_{OH} Min (V)	I_{OL}^1 (mA)	I_{OH}^1 (mA)
	Min (V)	Max (V)	Min (V)	Max (V)				
LVTTTL	-0.3	0.80	2.0	5.5	0.40	$V_{CCO} - 0.40$	8.0	-4.0
					0.20	$V_{CCO} - 0.20$	0.1	-0.1
LVCMOS 3.3	-0.3	0.80	2.0	5.5	0.40	$V_{CCO} - 0.40$	8.0	-4.0
					0.20	$V_{CCO} - 0.20$	0.1	-0.1
LVCMOS 2.5	-0.3	0.70	1.70	3.6	0.40	$V_{CCO} - 0.40$	8.0	-4.0
					0.20	$V_{CCO} - 0.20$	0.1	-0.1
LVCMOS 1.8 (4000V/B)	-0.3	0.63	1.17	3.6	0.40	$V_{CCO} - 0.45$	2.0	-2.0
					0.20	$V_{CCO} - 0.20$	0.1	-0.1
LVCMOS 1.8 (4000C/Z)	-0.3	$0.35 * V_{CC}$	$0.65 * V_{CC}$	3.6	0.40	$V_{CCO} - 0.45$	2.0	-2.0
					0.20	$V_{CCO} - 0.20$	0.1	-0.1
PCI 3.3 (4000V/B)	-0.3	1.08	1.5	5.5	$0.1 V_{CCO}$	$0.9 V_{CCO}$	1.5	-0.5
PCI 3.3 (4000C/Z)	-0.3	$0.3 * 3.3 * (V_{CC} / 1.8)$	$0.5 * 3.3 * (V_{CC} / 1.8)$	5.5	$0.1 V_{CCO}$	$0.9 V_{CCO}$	1.5	-0.5

1. The average DC current drawn by I/Os between adjacent bank GND connections, or between the last GND in an I/O bank and the end of the I/O bank, as shown in the logic signals connection table, shall not exceed $n * 8mA$. Where n is the number of I/Os between bank GND connections or between the last GND in a bank and the end of a bank.

ispMACH 4000V/B/C External Switching Characteristics

Over Recommended Operating Conditions

Parameter	Description ^{1, 2, 3}	-25		-27		-3		-35		Units
		Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
t _{PD}	5-PT bypass combinatorial propagation delay	—	2.5	—	2.7	—	3.0	—	3.5	ns
t _{PD_MC}	20-PT combinatorial propagation delay through macrocell	—	3.2	—	3.5	—	3.8	—	4.2	ns
t _S	GLB register setup time before clock	1.8	—	1.8	—	2.0	—	2.0	—	ns
t _{ST}	GLB register setup time before clock with T-type register	2.0	—	2.0	—	2.2	—	2.2	—	ns
t _{SIR}	GLB register setup time before clock, input register path	0.7	—	1.0	—	1.0	—	1.0	—	ns
t _{SIRZ}	GLB register setup time before clock with zero hold	1.7	—	2.0	—	2.0	—	2.0	—	ns
t _H	GLB register hold time after clock	0.0	—	0.0	—	0.0	—	0.0	—	ns
t _{HT}	GLB register hold time after clock with T-type register	0.0	—	0.0	—	0.0	—	0.0	—	ns
t _{HIR}	GLB register hold time after clock, input register path	0.9	—	1.0	—	1.0	—	1.0	—	ns
t _{HIRZ}	GLB register hold time after clock, input register path with zero hold	0.0	—	0.0	—	0.0	—	0.0	—	ns
t _{CO}	GLB register clock-to-output delay	—	2.2	—	2.7	—	2.7	—	2.7	ns
t _R	External reset pin to output delay	—	3.5	—	4.0	—	4.4	—	4.5	ns
t _{RW}	External reset pulse duration	1.5	—	1.5	—	1.5	—	1.5	-	ns
t _{P_{TOE/DIS}}	Input to output local product term output enable/disable	—	4.0	—	4.5	—	5.0	—	5.5	ns
t _{G_{P_{TOE/DIS}}}	Input to output global product term output enable/disable	—	5.0	—	6.5	—	8.0	—	8.0	ns
t _{G_{OE/DIS}}	Global OE input to output enable/disable	—	3.0	—	3.5	—	4.0	—	4.5	ns
t _{CW}	Global clock width, high or low	1.1	—	1.3	—	1.3	—	1.3	—	ns
t _{GW}	Global gate width low (for low transparent) or high (for high transparent)	1.1	—	1.3	—	1.3	—	1.3	—	ns
t _{WIR}	Input register clock width, high or low	1.1	—	1.3	—	1.3	—	1.3	—	ns
f _{MAX} ⁴	Clock frequency with internal feedback	—	400	—	333	—	322	—	322	MHz
f _{MAX} (Ext.)	Clock frequency with external feedback, [1/ (t _S + t _{CO})]	—	250	—	222	—	212	—	212	MHz

1. Timing numbers are based on default LVCMOS 1.8 I/O buffers. Use timing adjusters provided to calculate other standards.

Timing v.3.2

2. Measured using standard switching circuit, assuming GRP loading of 1 and 1 output switching.

3. Pulse widths and clock widths less than minimum will cause unknown behavior.

4. Standard 16-bit counter using GRP feedback.

ispMACH 4000Z External Switching Characteristics (Cont.)

Over Recommended Operating Conditions

Parameter	Description ^{1, 2, 3}	-45		-5		-75		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
t _{PD}	5-PT bypass combinatorial propagation delay	—	4.5	—	5.0	—	7.5	ns
t _{PD_MC}	20-PT combinatorial propagation delay through macrocell	—	5.8	—	6.0	—	8.0	ns
t _S	GLB register setup time before clock	2.9	—	3.0	—	4.5	—	ns
t _{ST}	GLB register setup time before clock with T-type register	3.1	—	3.2	—	4.7	—	ns
t _{SIR}	GLB register setup time before clock, input register path	1.3	—	1.3	—	1.4	—	ns
t _{SIRZ}	GLB register setup time before clock with zero hold	2.6	—	2.6	—	2.7	—	ns
t _H	GLB register hold time after clock	0.0	—	0.0	—	0.0	—	ns
t _{HT}	GLB register hold time after clock with T-type register	0.0	—	0.0	—	0.0	—	ns
t _{HIR}	GLB register hold time after clock, input register path	1.3	—	1.3	—	1.3	—	ns
t _{HIRZ}	GLB register hold time after clock, input register path with zero hold	0.0	—	0.0	—	0.0	—	ns
t _{CO}	GLB register clock-to-output delay	—	3.8	—	4.2	—	4.5	ns
t _R	External reset pin to output delay	—	7.5	—	7.5	—	9.0	ns
t _{RW}	External reset pulse duration	2.0	—	2.0	—	4.0	—	ns
t _{P_{TOE/DIS}}	Input to output local product term output enable/disable	—	8.2	—	8.5	—	9.0	ns
t _{G_PTOE/DIS}	Input to output global product term output enable/disable	—	10.0	—	10.0	—	10.5	ns
t _{G_OE/DIS}	Global OE input to output enable/disable	—	5.5	—	6.0	—	7.0	ns
t _{CW}	Global clock width, high or low	1.8	—	2.0	—	2.8	—	ns
t _{GW}	Global gate width low (for low transparent) or high (for high transparent)	1.8	—	2.0	—	2.8	—	ns
t _{WIR}	Input register clock width, high or low	1.8	—	2.0	—	2.8	—	ns
f _{MAX} ⁴	Clock frequency with internal feedback	—	200	—	200	—	168	MHz
f _{MAX} (Ext.)	clock frequency with external feedback, [1 / (t _S + t _{CO})]	—	150	—	139	—	111	MHz

1. Timing numbers are based on default LVCMOS 1.8 I/O buffers. Use timing adjusters provided to calculate other standards.

Timing v.2.2

2. Measured using standard switching GRP loading of 1 and 1 output switching.

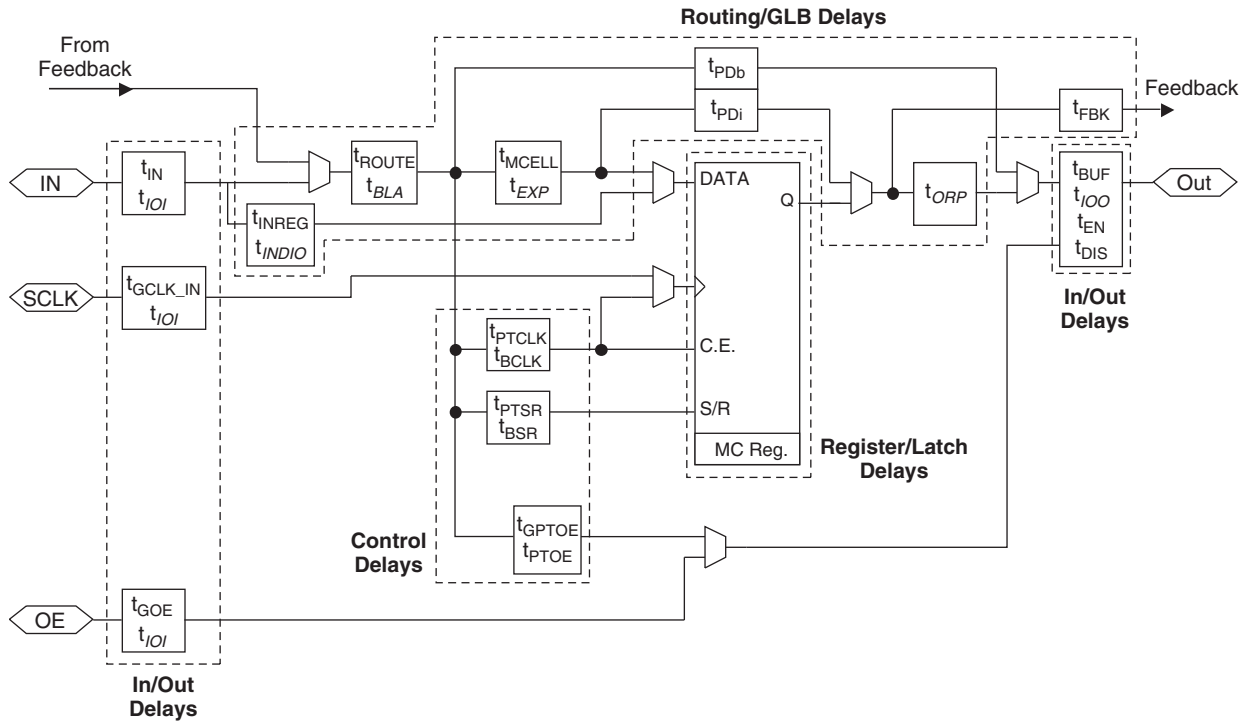
3. Pulse widths and clock widths less than minimum will cause unknown behavior.

4. Standard 16-bit counter using GRP feedback.

Timing Model

The task of determining the timing through the ispMACH 4000 family, like any CPLD, is relatively simple. The timing model provided in Figure 11 shows the specific delay paths. Once the implementation of a given function is determined either conceptually or from the software report file, the delay path of the function can easily be determined from the timing model. The Lattice design tools report the timing delays based on the same timing model for a particular design. Note that the internal timing parameters are given for reference only, and are not tested. The external timing parameters are tested and guaranteed for every device. For more information on the timing model and usage, refer to TN1004, [ispMACH 4000 Timing Model Design and Usage Guidelines](#).

Figure 11. ispMACH 4000 Timing Model



Note: Italicized items are optional delay adders.

ispMACH 4000V/B/C Internal Timing Parameters (Cont.)

Over Recommended Operating Conditions

Parameter	Description	-5		-75		-10		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
t _{GP} TOE	Global PT OE Delay	—	5.58	—	5.58	—	5.78	ns
t _P TOE	Macrocell PT OE Delay	—	3.58	—	4.28	—	4.28	ns

Timing v.3.2

Note: Internal Timing Parameters are not tested and are for reference only. Refer to the Timing Model in this data sheet for further details.

ispMACH 4000Z Internal Timing Parameters (Cont.)

Over Recommended Operating Conditions

Parameter	Description	-45		-5		-75		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
In/Out Delays								
t _{IN}	Input Buffer Delay	—	0.95	—	1.25	—	1.80	ns
t _{GOE}	Global OE Pin Delay	—	3.00	—	3.50	—	4.30	ns
t _{GCLK_IN}	Global Clock Input Buffer Delay	—	1.95	—	2.05	—	2.15	ns
t _{BUF}	Delay through Output Buffer	—	1.10	—	1.00	—	1.30	ns
t _{EN}	Output Enable Time	—	2.50	—	2.50	—	2.70	ns
t _{DIS}	Output Disable Time	—	2.50	—	2.50	—	2.70	ns
Routing/GLB Delays								
t _{ROUTE}	Delay through GRP	—	2.25	—	2.05	—	2.50	ns
t _{MCELL}	Macrocell Delay	—	0.65	—	0.65	—	1.00	ns
t _{INREG}	Input Buffer to Macrocell Register Delay	—	1.00	—	1.00	—	1.00	ns
t _{FBK}	Internal Feedback Delay	—	0.35	—	0.05	—	0.05	ns
t _{PDb}	5-PT Bypass Propagation Delay	—	0.20	—	0.70	—	1.90	ns
t _{PDi}	Macrocell Propagation Delay	—	0.45	—	0.65	—	1.00	ns
Register/Latch Delays								
t _S	D-Register Setup Time (Global Clock)	1.00	—	1.10	—	1.35	—	ns
t _{S_PT}	D-Register Setup Time (Product Term Clock)	2.10	—	1.90	—	2.45	—	ns
t _{ST}	T-Register Setup Time (Global Clock)	1.20	—	1.30	—	1.55	—	ns
t _{ST_PT}	T-register Setup Time (Product Term Clock)	2.30	—	2.10	—	2.75	—	ns
t _H	D-Register Hold Time	1.90	—	1.90	—	3.15	—	ns
t _{HT}	T-Resister Hold Time	1.90	—	1.90	—	3.15	—	ns
t _{SIR}	D-Input Register Setup Time (Global Clock)	1.30	—	1.10	—	0.75	—	ns
t _{SIR_PT}	D-Input Register Setup Time (Product Term Clock)	1.45	—	1.45	—	1.45	—	ns
t _{HIR}	D-Input Register Hold Time (Global Clock)	1.30	—	1.50	—	1.95	—	ns
t _{HIR_PT}	D-Input Register Hold Time (Product Term Clock)	1.00	—	1.00	—	1.18	—	ns
t _{COi}	Register Clock to Output/Feedback MUX Time	—	0.75	—	1.15	—	1.05	ns
t _{CES}	Clock Enable Setup Time	2.00	—	2.00	—	2.00	—	ns
t _{CEH}	Clock Enable Hold Time	0.00	—	0.00	—	0.00	—	ns
t _{SL}	Latch Setup Time (Global Clock)	1.00	—	1.00	—	1.65	—	ns
t _{SL_PT}	Latch Setup Time (Product Term Clock)	2.10	—	1.90	—	2.15	—	ns
t _{HL}	Latch Hold Time	2.00	—	2.00	—	1.17	—	ns
t _{GOi}	Latch Gate to Output/Feedback MUX Time	—	0.33	—	0.33	—	0.33	ns
t _{PDLi}	Propagation Delay through Transparent Latch to Output/Feedback MUX	—	0.25	—	0.25	—	0.25	ns
t _{SRI}	Asynchronous Reset or Set to Output/Feedback MUX Delay	—	0.97	—	0.97	—	0.28	ns
t _{SRR}	Asynchronous Reset or Set Recovery Delay	—	1.80	—	1.80	—	1.67	ns
Control Delays								
t _{BCLK}	GLB PT Clock Delay	—	1.55	—	1.55	—	1.25	ns
t _{PTCLK}	Macrocell PT Clock Delay	—	1.55	—	1.55	—	1.25	ns
t _{BSR}	GLB PT Set/Reset Delay	—	1.83	—	1.83	—	1.83	ns
t _{PTSR}	Macrocell PT Set/Reset Delay	—	1.83	—	1.83	—	2.72	ns
t _{GPTOE}	Global PT OE Delay	—	4.30	—	4.20	—	3.50	ns

ispMACH 4000V/B/C Timing Adders¹ (Cont.)

Adder Type	Base Parameter	Description	-5		-75		-10		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
Optional Delay Adders									
t_{INDIO}	t_{INREG}	Input register delay	—	1.00	—	1.00	—	1.00	ns
t_{EXP}	t_{MCELL}	Product term expander delay	—	0.33	—	0.33	—	0.33	ns
t_{ORP}	—	Output routing pool delay	—	0.05	—	0.05	—	0.05	ns
t_{BLA}	t_{ROUTE}	Additional block loading adder	—	0.05	—	0.05	—	0.05	ns
t_{IOI} Input Adjusters									
LVTTTL_in	$t_{IN}, t_{GCLK_IN}, t_{GOE}$	Using LVTTTL standard	—	0.60	—	0.60	—	0.60	ns
LVC MOS33_in	$t_{IN}, t_{GCLK_IN}, t_{GOE}$	Using LVC MOS 3.3 standard	—	0.60	—	0.60	—	0.60	ns
LVC MOS25_in	$t_{IN}, t_{GCLK_IN}, t_{GOE}$	Using LVC MOS 2.5 standard	—	0.60	—	0.60	—	0.60	ns
LVC MOS18_in	$t_{IN}, t_{GCLK_IN}, t_{GOE}$	Using LVC MOS 1.8 standard	—	0.00	—	0.00	—	0.00	ns
PCI_in	$t_{IN}, t_{GCLK_IN}, t_{GOE}$	Using PCI compatible input	—	0.60	—	0.60	—	0.60	ns
t_{IOO} Output Adjusters									
LVTTTL_out	t_{BUF}, t_{EN}, t_{DIS}	Output configured as TTL buffer	—	0.20	—	0.20	—	0.20	ns
LVC MOS33_out	t_{BUF}, t_{EN}, t_{DIS}	Output configured as 3.3V buffer	—	0.20	—	0.20	—	0.20	ns
LVC MOS25_out	t_{BUF}, t_{EN}, t_{DIS}	Output configured as 2.5V buffer	—	0.10	—	0.10	—	0.10	ns
LVC MOS18_out	t_{BUF}, t_{EN}, t_{DIS}	Output configured as 1.8V buffer	—	0.00	—	0.00	—	0.00	ns
PCI_out	t_{BUF}, t_{EN}, t_{DIS}	Output configured as PCI compatible buffer	—	0.20	—	0.20	—	0.20	ns
Slow Slew	t_{BUF}, t_{EN}	Output configured for slow slew rate	—	1.00	—	1.00	—	1.00	ns

Note: Open drain timing is the same as corresponding LVC MOS timing.

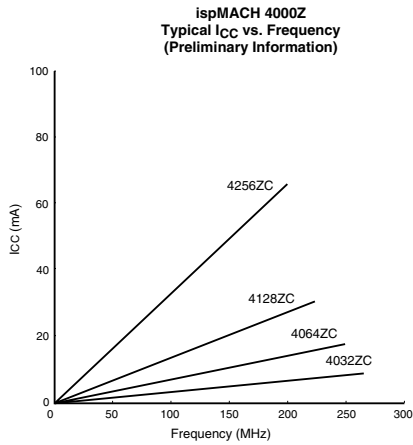
Timing v.3.2

1. Refer to TN1004, [ispMACH 4000 Timing Model Design and Usage Guidelines](#) for information regarding use of these adders.

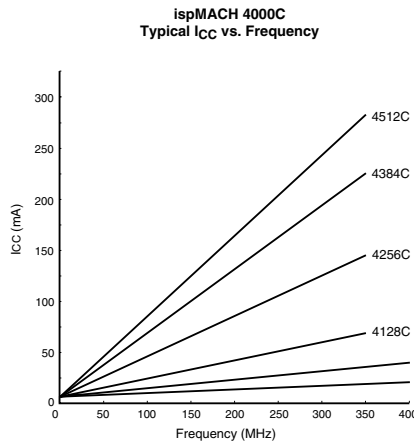
Boundary Scan Waveforms and Timing Specifications

Symbol	Parameter	Min.	Max.	Units
t_{BTCP}	TCK [BSCAN test] clock cycle	40	—	ns
t_{BTCH}	TCK [BSCAN test] pulse width high	20	—	ns
t_{BTCL}	TCK [BSCAN test] pulse width low	20	—	ns
t_{BTSU}	TCK [BSCAN test] setup time	8	—	ns
t_{BTH}	TCK [BSCAN test] hold time	10	—	ns
t_{BRF}	TCK [BSCAN test] rise and fall time	50	—	mV/ns
t_{BTO}	TAP controller falling edge of clock to valid output	—	10	ns
t_{BTOZ}	TAP controller falling edge of clock to data output disable	—	10	ns
t_{BTV}	TAP controller falling edge of clock to data output enable	—	10	ns
t_{BTCPSU}	BSCAN test Capture register setup time	8	—	ns
t_{BTCPH}	BSCAN test Capture register hold time	10	—	ns
t_{BTUCO}	BSCAN test Update reg, falling edge of clock to valid output	—	25	ns
t_{BTUOZ}	BSCAN test Update reg, falling edge of clock to output disable	—	25	ns
t_{BTUOV}	BSCAN test Update reg, falling edge of clock to output enable	—	25	ns

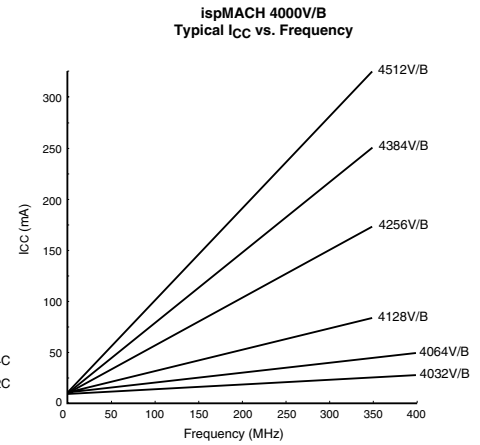
Power Consumption



Note: The devices are configured with maximum number of 16-bit counters, typical current at 1.8V, 25°C.



Note: The devices are configured with maximum number of 16-bit counters, typical current at 1.8V, 25°C.



Note: The devices are configured with maximum number of 16-bit counters, typical current at 3.3V, 2.5V, 25°C.

Power Estimation Coefficients¹

Device	A	B
ispMACH 4032V/B	11.3	0.010
ispMACH 4032C	1.3	0.010
ispMACH 4064V/B	11.5	0.010
ispMACH 4064C	1.5	0.010
ispMACH 4128V/B	11.5	0.011
ispMACH 4128C	1.5	0.011
ispMACH 4256V/B	12	0.011
ispMACH 4256C	2	0.011
ispMACH 4384V/B	12.5	0.013
ispMACH 4384C	2.5	0.013
ispMACH 4512V/B	13	0.013
ispMACH 4512C	3	0.013
ispMACH 4032ZC	0.010	0.010
ispMACH 4064ZC	0.011	0.010
ispMACH 4128ZC	0.012	0.010
ispMACH 4256ZC	0.013	0.010

1. For further information about the use of these coefficients, refer to TN1005, [Power Estimation in ispMACH 4000V/B/C/Z Devices](#).

**ispMACH 4064Z, 4128Z and 4256Z Logic Signal Connections:
132-Ball csBGA (Cont.)**

Ball Number	Bank Number	ispMACH 4064Z		ispMACH 4128Z		ispMACH 4256Z	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
E3	0	NC	-	B8	B^6	D12	D^6
F2	0	A12	A^12	B9	B^7	D10	D^5
F1	0	A13	A^13	B10	B^8	D8	D^4
F3	0	A14	A^14	B12	B^9	D6	D^3
G1	0	A15	A^15	B13	B^10	D4	D^2
G2	0	I	-	B14	B^11	D2	D^1
G3	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
H2	0	NC	-	C14	C^11	E2	E^1
H1	0	B15	B^15	C13	C^10	E4	E^2
H3	0	B14	B^14	C12	C^9	E6	E^3
J1	0	B13	B^13	C10	C^8	E8	E^4
J2	0	B12	B^12	C9	C^7	E10	E^5
J3	0	NC	-	C8	C^6	E12	E^6
K2	0	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-
K1	0	NC	-	C6	C^5	F2	F^1
K3	0	B11	B^11	C5	C^4	F4	F^2
L2	0	B10	B^10	C4	C^3	F6	F^3
L1	0	B9	B^9	C2	C^2	F8	F^4
L3	0	B8	B^8	C1	C^1	F10	F^5
M1	0	I	-	C0	C^0	F12	F^6
M2	0	NC	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
N1	-	TCK	-	TCK	-	TCK	-
P1	-	VCC	-	VCC	-	VCC	-
P2	-	GND	-	GND	-	GND	-
N2	0	I	-	D14	D^11	G12	G^6
P3	0	B7	B^7	D13	D^10	G10	G^5
M3	0	B6	B^6	D12	D^9	G8	G^4
N3	0	B5	B^5	D10	D^8	G6	G^3
P4	0	B4	B^4	D9	D^7	G4	G^2
M4	0	NC	-	D8	D^6	G2	G^1
N4	0	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-
P5	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
N5	0	NC	-	D6	D^5	H12	H^6
M5	0	B3	B^3	D5	D^4	H10	H^5
N6	0	B2	B^2	D4	D^3	H8	H^4
P6	0	B1	B^1	D2	D^2	H6	H^3
M6	0	B0	B^0	D1	D^1	H4	H^2
P7	0	NC	-	D0	D^0	H2	H^1
N7	0	CLK1/I	-	CLK1/I	-	CLK1/I	-
M7	1	CLK2/I	-	CLK2/I	-	CLK2/I	-
N8	-	VCC	-	VCC	-	VCC	-

ispMACH 4128V and 4256V Logic Signal Connections: 144-Pin TQFP (Cont.)

Pin Number	Bank Number	ispMACH 4128V		ispMACH 4256V	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
86	1	F12	F ⁹	L8	L ⁴
87	1	F13	F ¹⁰	L6	L ³
88	1	F14	F ¹¹	L4	L ²
89	1	NC ²	-	I ²	-
90	1	GND (Bank 1) ¹	-	NC ¹	-
91	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-
92	1	NC ²	-	I ²	-
93	1	G14	G ¹¹	M2	M ¹
94	1	G13	G ¹⁰	M4	M ²
95	1	G12	G ⁹	M6	M ³
96	1	G10	G ⁸	M8	M ⁴
97	1	G9	G ⁷	M10	M ⁵
98	1	G8	G ⁶	M12	M ⁶
99	1	GND (Bank 1)	-	GND (Bank 1)	-
100	1	G6	G ⁵	N2	N ¹
101	1	G5	G ⁴	N4	N ²
102	1	G4	G ³	N6	N ³
103	1	G2	G ²	N8	N ⁴
104	1	G1	G ¹	N10	N ⁵
105	1	G0	G ⁰	N12	N ⁶
106	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-
107	-	TDO	-	TDO	-
108	-	VCC	-	VCC	-
109	-	GND	-	GND	-
110	1	NC ²	-	I ²	-
111	1	H14	H ¹¹	O12	O ⁶
112	1	H13	H ¹⁰	O10	O ⁵
113	1	H12	H ⁹	O8	O ⁴
114	1	H10	H ⁸	O6	O ³
115	1	H9	H ⁷	O4	O ²
116	1	H8	H ⁶	O2	O ¹
117	1	NC ²	-	I ²	-
118	1	GND (Bank 1)	-	GND (Bank 1)	-
119	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-
120	1	H6	H ⁵	P12	P ⁶
121	1	H5	H ⁴	P10	P ⁵
122	1	H4	H ³	P8	P ⁴
123	1	H2	H ²	P6	P ³
124	1	H1	H ¹	P4	P ²
125	1	H0/GOE1	H ⁰	P2/GOE1	P ¹
126	1	CLK3/I	-	CLK3/I	-
127	0	GND (Bank 0)	-	GND (Bank 0)	-
128	0	CLK0/I	-	CLK0/I	-

ispMACH 4128V and 4256V Logic Signal Connections: 144-Pin TQFP (Cont.)

Pin Number	Bank Number	ispMACH 4128V		ispMACH 4256V	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
129	-	VCC	-	VCC	-
130	0	A0/GOE0	A^0	A2/GOE0	A^1
131	0	A1	A^1	A4	A^2
132	0	A2	A^2	A6	A^3
133	0	A4	A^3	A8	A^4
134	0	A5	A^4	A10	A^5
135	0	A6	A^5	A12	A^6
136	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-
137	0	GND (Bank 0)	-	GND (Bank 0)	-
138	0	A8	A^6	B2	B^1
139	0	A9	A^7	B4	B^2
140	0	A10	A^8	B6	B^3
141	0	A12	A^9	B8	B^4
142	0	A13	A^10	B10	B^5
143	0	A14	A^11	B12	B^6
144	0	NC ²	-	I ²	-

1. For device migration considerations, these NC pins are GND pins for I/O banks in ispMACH 4128V devices.
2. For device migration considerations, these NC pins are input signal pins in ispMACH 4256V devices.

ispMACH 4256V/B/C/Z, 4384V/B/C, 4512V/B/C, Logic Signal Connections: 176-Pin TQFP

Pin Number	Bank Number	ispMACH 4256V/B/C/Z		ispMACH 4384V/B/C		ispMACH 4512V/B/C	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
1	-	NC	-	NC	-	NC	-
2	-	GND	-	GND	-	GND	-
3	-	TDI	-	TDI	-	TDI	-
4	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
5	0	C14	C^7	C14	C^7	C14	C^7
6	0	C12	C^6	C12	C^6	C12	C^6
7	0	C10	C^5	C10	C^5	C10	C^5
8	0	C8	C^4	C8	C^4	C8	C^4
9	0	C6	C^3	C6	C^3	C6	C^3
10	0	C4	C^2	C4	C^2	C4	C^2
11	0	C2	C^1	C2	C^1	C2	C^1
12	0	C0	C^0	C0	C^0	C0	C^0
13	0	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-
14	0	D14	D^7	E14	E^7	G14	G^7
15	0	D12	D^6	E12	E^6	G12	G^6
16	0	D10	D^5	E10	E^5	G10	G^5
17	0	D8	D^4	E8	E^4	G8	G^4
18	0	D6	D^3	E6	E^3	G6	G^3

**ispMACH 4256V/B/C/Z, 4384V/B/C, 4512V/B/C, Logic Signal Connections:
176-Pin TQFP (Cont.)**

Pin Number	Bank Number	ispMACH 4256V/B/C/Z		ispMACH 4384V/B/C		ispMACH 4512V/B/C	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
60	0	H8	H ⁴	L8	L ⁴	P8	P ⁴
61	0	H6	H ³	L6	L ³	P6	P ³
62	0	H4	H ²	L4	L ²	P4	P ²
63	0	H2	H ¹	L2	L ¹	P2	P ¹
64	0	H0	H ⁰	L0	L ⁰	P0	P ⁰
65	-	GND	-	GND	-	GND	-
66	0	CLK1/I	-	CLK1/I	-	CLK1/I	-
67	1	GND (Bank 1)	-	GND (Bank 1)	-	GND (Bank 1)	-
68	1	CLK2/I	-	CLK2/I	-	CLK2/I	-
69	-	VCC	-	VCC	-	VCC	-
70	1	I0	I ⁰	M0	M ⁰	AX0	AX ⁰
71	1	I2	I ¹	M2	M ¹	AX2	AX ¹
72	1	I4	I ²	M4	M ²	AX4	AX ²
73	1	I6	I ³	M6	M ³	AX6	AX ³
74	1	I8	I ⁴	M8	M ⁴	AX8	AX ⁴
75	1	I10	I ⁵	M10	M ⁵	AX10	AX ⁵
76	1	I12	I ⁶	M12	M ⁶	AX12	AX ⁶
77	1	I14	I ⁷	M14	M ⁷	AX14	AX ⁷
78	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-	VCCO (Bank 1)	-
79	1	GND (Bank 1)	-	GND (Bank 1)	-	GND (Bank 1)	-
80	1	J0	J ⁰	N0	N ⁰	BX0	BX ⁰
81	1	J2	J ¹	N2	N ¹	BX2	BX ¹
82	1	J4	J ²	N4	N ²	BX4	BX ²
83	1	J6	J ³	N6	N ³	BX6	BX ³
84	1	J8	J ⁴	N8	N ⁴	BX8	BX ⁴
85	1	J10	J ⁵	N10	N ⁵	BX10	BX ⁵
86	1	J12	J ⁶	N12	N ⁶	BX12	BX ⁶
87	1	J14	J ⁷	N14	N ⁷	BX14	BX ⁷
88	-	VCC	-	VCC	-	VCC	-
89	-	NC	-	NC	-	NC	-
90	-	GND	-	GND	-	GND	-
91	-	TMS	-	TMS	-	TMS	-
92	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-	VCCO (Bank 1)	-
93	1	K14	K ⁷	O14	O ⁷	CX14	CX ⁷
94	1	K12	K ⁶	O12	O ⁶	CX12	CX ⁶
95	1	K10	K ⁵	O10	O ⁵	CX10	CX ⁵
96	1	K8	K ⁴	O8	O ⁴	CX8	CX ⁴
97	1	K6	K ³	O6	O ³	CX6	CX ³
98	1	K4	K ²	O4	O ²	CX4	CX ²
99	1	K2	K ¹	O2	O ¹	CX2	CX ¹
100	1	K0	K ⁰	O0	O ⁰	CX0	CX ⁰

**ispMACH 4256V/B/C, 4384V/B/C, 4512V/B/C Logic Signal Connections:
256-Ball ftBGA/fpBGA**

Ball Number	I/O Bank	ispMACH 4256V/B/C 128-I/O		ispMACH 4256V/B/C 160-I/O		ispMACH 4384V/B/C		ispMACH 4512V/B/C	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
-	-	-	-	-	-	VCC	-	VCC	-
-	-	GND	-	GND	-	GND	-	GND	-
C3	-	TDI	-	TDI	-	TDI	-	TDI	-
-	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
B1	0	C14	C^7	C14	C^9	C14	C^7	C14	C^7
F5	0	C12	C^6	C12	C^8	C12	C^6	C12	C^6
D3	0	C10	C^5	C10	C^7	C10	C^5	C10	C^5
C1	0	C8	C^4	C9	C^6	C8	C^4	C8	C^4
C2	0	C6	C^3	C8	C^5	C6	C^3	C6	C^3
E3	0	C4	C^2	C6	C^4	C4	C^2	C4	C^2
D2	0	C2	C^1	C4	C^3	C2	C^1	C2	C^1
F6	0	C0	C^0	C2	C^2	C0	C^0	C0	C^0
D1	0	NC	-	C1	C^1	F6	F^3	H0	H^0
E2	0	NC	-	C0	C^0	F4	F^2	H4	H^1
E4	0	NC	-	NC	-	D6	D^3	F4	F^2
G5	0	NC	-	NC	-	D4	D^2	F6	F^3
E1	0	NC	-	NC	-	NC	-	F8	F^4
-	0	-	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
-	0	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-
F2	0	NC	-	NC	-	NC	-	F10	F^5
F1	0	NC	-	NC	-	D2	D^1	F12	F^6
G1	0	NC	-	NC	-	D0	D^0	F14	F^7
G6	0	NC	-	D14	D^9	F2	F^1	H8	H^2
G4	0	NC	-	D12	D^8	F0	F^0	H12	H^3
H6	0	D14	D^7	D10	D^7	E14	E^7	G14	G^7
G3	0	D12	D^6	D9	D^6	E12	E^6	G12	G^6
H5	0	D10	D^5	D8	D^5	E10	E^5	G10	G^5
G2	0	D8	D^4	D6	D^4	E8	E^4	G8	G^4
H1	0	D6	D^3	D4	D^3	E6	E^3	G6	G^3
H2	0	D4	D^2	D2	D^2	E4	E^2	G4	G^2
H3	0	D2	D^1	D1	D^1	E2	E^1	G2	G^1
H4	0	D0	D^0	D0	D^0	E0	E^0	G0	G^0
-	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
-	0	-	-	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-
J4	0	E0	E^0	E0	E^0	H0	H^0	J0	J^0
J3	0	E2	E^1	E1	E^1	H2	H^1	J2	J^1
J2	0	E4	E^2	E2	E^2	H4	H^2	J4	J^2
J1	0	E6	E^3	E4	E^3	H6	H^3	J6	J^3
K1	0	E8	E^4	E6	E^4	H8	H^4	J8	J^4
J5	0	E10	E^5	E8	E^5	H10	H^5	J10	J^5
K2	0	E12	E^6	E9	E^6	H12	H^6	J12	J^6

**ispMACH 4256V/B/C, 4384V/B/C, 4512V/B/C Logic Signal Connections:
256-Ball ftBGA/fpBGA (Cont.)**

Ball Number	I/O Bank	ispMACH 4256V/B/C 128-I/O		ispMACH 4256V/B/C 160-I/O		ispMACH 4384V/B/C		ispMACH 4512V/B/C	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
R5	0	NC	-	NC	-	NC	-	L4	L^1
T5	0	NC	-	NC	-	I2	I^1	L8	L^2
R6	0	NC	-	NC	-	I0	I^0	L12	L^3
T6	0	NC	-	H14	H^9	G12	G^6	M8	M^2
N7	0	NC	-	H12	H^8	G14	G^7	M12	M^3
P7	0	H14	H^7	H10	H^7	L14	L^7	P14	P^7
R7	0	H12	H^6	H9	H^6	L12	L^6	P12	P^6
L8	0	H10	H^5	H8	H^5	L10	L^5	P10	P^5
T7	0	H8	H^4	H6	H^4	L8	L^4	P8	P^4
M8	0	H6	H^3	H4	H^3	L6	L^3	P6	P^3
N8	0	H4	H^2	H2	H^2	L4	L^2	P4	P^2
R8	0	H2	H^1	H1	H^1	L2	L^1	P2	P^1
P8	0	H0	H^0	H0	H^0	L0	L^0	P0	P^0
-	-	GND	-	GND	-	GND	-	GND	-
T8	0	CLK1/I	-	CLK1/I	-	CLK1/I	-	CLK1/I	-
-	1	GND (Bank 1)	-	GND (Bank 1)	-	GND (Bank 1)	-	GND (Bank 1)	-
N9	1	CLK2/I	-	CLK2/I	-	CLK2/I	-	CLK2/I	-
-	-	VCC	-	VCC	-	VCC	-	VCC	-
P9	1	I0	I^0	I0	I^0	M0	M^0	AX0	AX^0
R9	1	I2	I^1	I1	I^1	M2	M^1	AX2	AX^1
T9	1	I4	I^2	I2	I^2	M4	M^2	AX4	AX^2
T10	1	I6	I^3	I4	I^3	M6	M^3	AX6	AX^3
R10	1	I8	I^4	I6	I^4	M8	M^4	AX8	AX^4
M9	1	I10	I^5	I8	I^5	M10	M^5	AX10	AX^5
P10	1	I12	I^6	I9	I^6	M12	M^6	AX12	AX^6
L9	1	I14	I^7	I10	I^7	M14	M^7	AX14	AX^7
N10	1	NC	-	I12	I^8	BX14	BX^7	DX0	DX^0
T11	1	NC	-	I14	I^9	BX12	BX^6	DX4	DX^1
R11	1	NC	-	NC	-	P0	P^0	EX0	EX^0
T12	1	NC	-	NC	-	P2	P^1	EX4	EX^1
N12	1	NC	-	NC	-	NC	-	EX8	EX^2
-	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-	VCCO (Bank 1)	-	VCCO (Bank 1)	-
-	1	GND (Bank 1)	-	GND (Bank 1)	-	GND (Bank 1)	-	GND (Bank 1)	-
R12	1	NC	-	NC	-	NC	-	EX12	EX^3
T13	1	NC	-	J0	J^0	BX10	BX^5	DX8	DX^2
P12	1	NC	-	J1	J^1	BX8	BX^4	DX12	DX^3
M10	1	J0	J^0	J2	J^2	N0	N^0	BX0	BX^0
R13	1	J2	J^1	J4	J^3	N2	N^1	BX2	BX^1
L10	1	J4	J^2	J6	J^4	N4	N^2	BX4	BX^2
T14	1	J6	J^3	J8	J^5	N6	N^3	BX6	BX^3
M11	1	J8	J^4	J9	J^6	N8	N^4	BX8	BX^4

ispMACH 4000B (2.5V) Industrial Devices (Cont.)

Family	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4384B	LC4384B-5FT256I	384	2.5	5	ftBGA	256	192	I
	LC4384B-75FT256I	384	2.5	7.5	ftBGA	256	192	I
	LC4384B-10FT256I	384	2.5	10	ftBGA	256	192	I
	LC4384B-5F256I ¹	384	2.5	5	fpBGA	256	192	I
	LC4384B-75F256I ¹	384	2.5	7.5	fpBGA	256	192	I
	LC4384B-10F256I ¹	384	2.5	10	fpBGA	256	192	I
	LC4384B-5T176I	384	2.5	5	TQFP	176	128	I
	LC4384B-75T176I	384	2.5	7.5	TQFP	176	128	I
	LC4384B-10T176I	384	2.5	10	TQFP	176	128	I
LC4512B	LC4512B-5FT256I	512	2.5	5	ftBGA	256	208	I
	LC4512B-75FT256I	512	2.5	7.5	ftBGA	256	208	I
	LC4512B-10FT256I	512	2.5	10	ftBGA	256	208	I
	LC4512B-5F256I ¹	512	2.5	5	fpBGA	256	208	I
	LC4512B-75F256I ¹	512	2.5	7.5	fpBGA	256	208	I
	LC4512B-10F256I ¹	512	2.5	10	fpBGA	256	208	I
	LC4512B-5T176I	512	2.5	5	TQFP	176	128	I
	LC4512B-75T176I	512	2.5	7.5	TQFP	176	128	I
	LC4512B-10T176I	512	2.5	10	TQFP	176	128	I

1. Use ftBGA package. fpBGA package devices have been discontinued via PCN#14A-07.

ispMACH 4000V (3.3V) Commercial Devices

Device	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4032V	LC4032V-25T48C	32	3.3	2.5	TQFP	48	32	C
	LC4032V-5T48C	32	3.3	5	TQFP	48	32	C
	LC4032V-75T48C	32	3.3	7.5	TQFP	48	32	C
	LC4032V-25T44C	32	3.3	2.5	TQFP	44	30	C
	LC4032V-5T44C	32	3.3	5	TQFP	44	30	C
	LC4032V-75T44C	32	3.3	7.5	TQFP	44	30	C
LC4064V	LC4064V-25T100C	64	3.3	2.5	TQFP	100	64	C
	LC4064V-5T100C	64	3.3	5	TQFP	100	64	C
	LC4064V-75T100C	64	3.3	7.5	TQFP	100	64	C
	LC4064V-25T48C	64	3.3	2.5	TQFP	48	32	C
	LC4064V-5T48C	64	3.3	5	TQFP	48	32	C
	LC4064V-75T48C	64	3.3	7.5	TQFP	48	32	C
	LC4064V-25T44C	64	3.3	2.5	TQFP	44	30	C
	LC4064V-5T44C	64	3.3	5	TQFP	44	30	C
	LC4064V-75T44C	64	3.3	7.5	TQFP	44	30	C

ispMACH 4000V (3.3V) Commercial Devices (Cont.)

Device	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4128V	LC4128V-27T144C	128	3.3	2.7	TQFP	144	96	C
	LC4128V-5T144C	128	3.3	5	TQFP	144	96	C
	LC4128V-75T144C	128	3.3	7.5	TQFP	144	96	C
	LC4128V-27T128C	128	3.3	2.7	TQFP	128	92	C
	LC4128V-5T128C	128	3.3	5	TQFP	128	92	C
	LC4128V-75T128C	128	3.3	7.5	TQFP	128	92	C
	LC4128V-27T100C	128	3.3	2.7	TQFP	100	64	C
	LC4128V-5T100C	128	3.3	5	TQFP	100	64	C
	LC4128V-75T100C	128	3.3	7.5	TQFP	100	64	C
LC4256V	LC4256V-3FT256AC	256	3.3	3	ftBGA	256	128	C
	LC4256V-5FT256AC	256	3.3	5	ftBGA	256	128	C
	LC4256V-75FT256AC	256	3.3	7.5	ftBGA	256	128	C
	LC4256V-3FT256BC	256	3.3	3	ftBGA	256	160	C
	LC4256V-5FT256BC	256	3.3	5	ftBGA	256	160	C
	LC4256V-75FT256BC	256	3.3	7.5	ftBGA	256	160	C
	LC4256V-3F256AC ¹	256	3.3	3	fpBGA	256	128	C
	LC4256V-5F256AC ¹	256	3.3	5	fpBGA	256	128	C
	LC4256V-75F256AC ¹	256	3.3	7.5	fpBGA	256	128	C
	LC4256V-3F256BC ¹	256	3.3	3	fpBGA	256	160	C
	LC4256V-5F256BC ¹	256	3.3	5	fpBGA	256	160	C
	LC4256V-75F256BC ¹	256	3.3	7.5	fpBGA	256	160	C
	LC4256V-3T176C	256	3.3	3	TQFP	176	128	C
	LC4256V-5T176C	256	3.3	5	TQFP	176	128	C
	LC4256V-75T176C	256	3.3	7.5	TQFP	176	128	C
	LC4256V-3T144C	256	3.3	3	TQFP	144	96	C
	LC4256V-5T144C	256	3.3	5	TQFP	144	96	C
	LC4256V-75T144C	256	3.3	7.5	TQFP	144	96	C
	LC4256V-3T100C	256	3.3	3	TQFP	100	64	C
	LC4256V-5T100C	256	3.3	5	TQFP	100	64	C
LC4256V-75T100C	256	3.3	7.5	TQFP	100	64	C	
LC4384V	LC4384V-35FT256C	384	3.3	3.5	ftBGA	256	192	C
	LC4384V-5FT256C	384	3.3	5	ftBGA	256	192	C
	LC4384V-75FT256C	384	3.3	7.5	ftBGA	256	192	C
	LC4384V-35F256C ¹	384	3.3	3.5	fpBGA	256	192	C
	LC4384V-5F256C ¹	384	3.3	5	fpBGA	256	192	C
	LC4384V-75F256C ¹	384	3.3	7.5	fpBGA	256	192	C
	LC4384V-35T176C	384	3.3	3.5	TQFP	176	128	C
	LC4384V-5T176C	384	3.3	5	TQFP	176	128	C
	LC4384V-75T176C	384	3.3	7.5	TQFP	176	128	C

ispMACH 4000V (3.3V) Lead-Free Commercial Devices (Cont.)

Device	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4256V	LC4256V-3FTN256AC	256	3.3	3	Lead-free ftBGA	256	128	C
	LC4256V-5FTN256AC	256	3.3	5	Lead-free ftBGA	256	128	C
	LC4256V-75FTN256AC	256	3.3	7.5	Lead-free ftBGA	256	128	C
	LC4256V-3FTN256BC	256	3.3	3	Lead-free ftBGA	256	160	C
	LC4256V-5FTN256BC	256	3.3	5	Lead-free ftBGA	256	160	C
	LC4256V-75FTN256BC	256	3.3	7.5	Lead-free ftBGA	256	160	C
	LC4256V-3FN256AC ¹	256	3.3	3	Lead-free fpBGA	256	128	C
	LC4256V-5FN256AC ¹	256	3.3	5	Lead-free fpBGA	256	128	C
	LC4256V-75FN256AC ¹	256	3.3	7.5	Lead-free fpBGA	256	128	C
	LC4256V-3FN256BC ¹	256	3.3	3	Lead-free fpBGA	256	160	C
	LC4256V-5FN256BC ¹	256	3.3	5	Lead-free fpBGA	256	160	C
	LC4256V-75FN256BC ¹	256	3.3	7.5	Lead-free fpBGA	256	160	C
	LC4256V-3TN176C	256	3.3	3	Lead-free TQFP	176	128	C
	LC4256V-5TN176C	256	3.3	5	Lead-free TQFP	176	128	C
	LC4256V-75TN176C	256	3.3	7.5	Lead-free TQFP	176	128	C
	LC4256V-3TN144C	256	3.3	3	Lead-free TQFP	144	96	C
	LC4256V-5TN144C	256	3.3	5	Lead-free TQFP	144	96	C
	LC4256V-75TN144C	256	3.3	7.5	Lead-free TQFP	144	96	C
	LC4256V-3TN100C	256	3.3	3	Lead-free TQFP	100	64	C
	LC4256V-5TN100C	256	3.3	5	Lead-free TQFP	100	64	C
LC4256V-75TN100C	256	3.3	7.5	Lead-free TQFP	100	64	C	
LC4384V	LC4384V-35FTN256C	384	3.3	3.5	Lead-free ftBGA	256	192	C
	LC4384V-5FTN256C	384	3.3	5	Lead-free ftBGA	256	192	C
	LC4384V-75FTN256C	384	3.3	7.5	Lead-free ftBGA	256	192	C
	LC4384V-35FN256C ¹	384	3.3	3.5	Lead-free fpBGA	256	192	C
	LC4384V-5FN256C ¹	384	3.3	5	Lead-free fpBGA	256	192	C
	LC4384V-75FN256C ¹	384	3.3	7.5	Lead-free fpBGA	256	192	C
	LC4384V-35TN176C	384	3.3	3.5	Lead-free TQFP	176	128	C
	LC4384V-5TN176C	384	3.3	5	Lead-free TQFP	176	128	C
LC4384V-75TN176C	384	3.3	7.5	Lead-free TQFP	176	128	C	
LC4512V	LC4512V-35FTN256C	512	3.3	3.5	Lead-free ftBGA	256	208	C
	LC4512V-5FTN256C	512	3.3	5	Lead-free ftBGA	256	208	C
	LC4512V-75FTN256C	512	3.3	7.5	Lead-free ftBGA	256	208	C
	LC4512V-35FN256C ¹	512	3.3	3.5	Lead-free fpBGA	256	208	C
	LC4512V-5FN256C ¹	512	3.3	5	Lead-free fpBGA	256	208	C
	LC4512V-75FN256C ¹	512	3.3	7.5	Lead-free fpBGA	256	208	C
	LC4512V-35TN176C	512	3.3	3.5	Lead-free TQFP	176	128	C
	LC4512V-5TN176C	512	3.3	5	Lead-free TQFP	176	128	C
	LC4512V-75TN176C	512	3.3	7.5	Lead-free TQFP	176	128	C

1. Use ftBGA package. fpBGA package devices have been discontinued via PCN#14A-07.